

## SEMICONDUCTOR DEVICE

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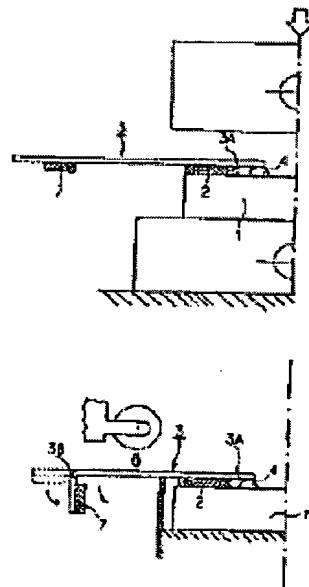
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### Abstract of JP4085837

**PURPOSE:** To obtain an ultra-thin package which can contain a large semiconductor chip by a constitution in which a lead is secured onto the circuit forming face of a semiconductor through an insulating adhesive layer and extended to the rear surface of the semiconductor chip to be secured in place through an insulating adhesive layer.

**CONSTITUTION:** A lead frame provided with an insulating adhesive film 2 is mounted on the circuit forming face of a semiconductor chip 1 having a solder bump electrode 4 and press bonded by means of a heating block thus adhering the insulating adhesive film 2 onto the circuit forming face of the semiconductor chip 1 and bonding the inner lead 3A of a lead 3 to the bump electrode 4 of the semiconductor chip 1. The outer lead 3B of the lead 3 is then bent at the tip thereof and further bent in parallel with the side of the semiconductor chip 1 by means of a roller or the like thus thermocompressing an insulating adhesive film 7 to the rear surface of the semiconductor chip 1. A resin block member 5 is then formed on the circuit forming face of the semiconductor chip 1, liquid resin is dripped and cured, thus completing a package.

According to the constitution, the package can be fabricated with dimensions substantially same as those of the semiconductor chip.



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